



IPC-2252

Design Guide for RF/ Microwave Circuit Boards

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A standard developed by IPC

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June 1995

2215 Sanders Road, Northbrook, IL 60062-6135
Tel. 847.509.9700 Fax 847.509.9798
www.ipc.org

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Developed by the High Speed/High Frequency Design Task Group (D-21b) of the High Speed/High Frequency Committee (D-20) of IPC

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Contact:

IPC
2215 Sanders Road
Northbrook, Illinois
60062-6135
Tel 847 509.9700
Fax 847 509.9798

Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the High Speed/High Frequency Design Task Group (D-21b) of the High Speed/High Frequency Committee (D-20) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

High Speed/High Frequency Committee	High Speed/High Frequency Design Task Group	Technical Liaison of the IPC Board of Directors
Chair Tom Bresnan Kulicke & Soffa	Chair Nicholas G. Paultre NIST	William Beckenbaugh, Ph.D. Sanmina-SCI Corporation

High Speed/High Frequency Design Task Group

Amit Bhardwaj, Polar Instruments, Ltd.	Steven Fecanin, DuPont Engineering Polymers Automotive	Roy Leventhal, CommWorks
Robert J. Black, Northrop Grumman Corporation	Margie Hillsman, GE Transportation Systems	Rene R. Martinez, TRW Electronics & Technology Division
Ronald J. Brock, NSWC - Crane	David H. Hoover, Multek	Deepak K. Pai, C.I.D., Advanced Information Systems
John Bushie, Taconic, Advanced Dielectric Division	Thomas E. Kemp, Rockwell Collins	John Reynolds, Rogers Corporation
Byron Case, L-3 Communications	Roy M. Keen, Rockwell Collins	Roberta Ross, Taconic Advanced Dielectric Division
Christine R. Coapman, Delphi Delco Electronics Systems	Robert J. Konsowitz, GIL Technologies	Lowell Sherman, Defense Supply Center Columbus
Theodore Edwards, Dynaco Corporation	George T. Kotecki, Northrop Grumman Corporation	G. Robert Traut, Rogers Corporation
Werner Engelmaier, Engelmaier Associates, L.C.	Cary Kyhl, Raytheon Systems Company	Philip R Wellington, L-3 Communications

Table of Contents

1 GENERAL	1	6 ELECTRICAL CHARACTERISTICS	11
1.1 Purpose	1	6.1 Stripline	12
1.2 Scope	1	6.1.1 Characteristic Impedance of Stripline	12
1.3 Terms and Definitions	1	6.1.2 Attenuation in Stripline.....	13
2 APPLICABLE DOCUMENTS.....	3	6.2 Asymmetric Stripline	13
2.1 IPC	3	6.3 Microstrip	14
2.2 American Society for Testing and Materials	3	6.3.1 Characteristic Impedance and Effective Permittivity of Microstrip	14
2.3 Society of Automotive Engineers	3	6.3.2 Attenuation in Microstrip.....	16
2.4 American Society of Mechanical Engineers.....	3		
2.5 International Organization for Standardization ...	3		
2.6 Reference Information.....	3		
3 DESIGN CONSIDERATIONS.....	3		
3.1 Initial Input.....	3		
3.2 Design Options.....	3		
3.3 Transmission Line Type, Materials, and Components	3		
3.4 Electrical Design	5		
3.5 Mechanical Design.....	5		
3.6 Preliminary Design Review	5		
3.7 Breadboard.....	5		
3.8 Prototype.....	5		
3.9 Documentation.....	5		
3.10 Final Design Review.....	5		
4 DOCUMENTATION REQUIREMENTS	5		
4.1 Design Features Listing	5		
4.2 Master Drawing.....	5		
4.3 Master Pattern	6		
5 MATERIALS	6		
5.1 Microwave Printed Circuit Board Materials	6		
5.1.1 Substrate Selection	6		
5.2 Bonding Films.....	8		
5.2.1 Thermoplastic Bonding Films.....	8		
5.2.2 Thermoset Bonding Films.....	8		
5.2.3 PTFE Bonding Considerations	8		
5.3 Metals	9		
5.3.1 Cladding.....	9		
5.3.2 Metal Plating	9		
5.3.3 Galvanic Corrosion	10		
5.3.4 Chromate Conversion Coating.....	11		
5.4 Conformal Coating.....	11		
5.4.1 General Caution.....	11		
5.4.2 PTFE Considerations.....	11		
6 ELECTRICAL CHARACTERISTICS	11		
6.1 Stripline	12		
6.1.1 Characteristic Impedance of Stripline	12		
6.1.2 Attenuation in Stripline.....	13		
6.2 Asymmetric Stripline	13		
6.3 Microstrip	14		
6.3.1 Characteristic Impedance and Effective Permittivity of Microstrip	14		
6.3.2 Attenuation in Microstrip.....	16		
7 DETAILED BOARD REQUIREMENTS	16		
7.1 Machined Features	16		
7.1.1 Dimensioning and Tolerancing	16		
7.1.2 Plated-Through Holes	17		
7.1.3 Unplated Holes.....	19		
7.1.4 Depth Pockets and Slots	19		
7.1.5 Inner-Layer Access Machining	19		
7.1.6 Periphery.....	19		
7.1.7 Numerically Controlled (NC) Equipment	19		
7.1.8 Dimensional Inspection.....	19		
7.2 Imaging	19		
7.2.1 Artwork.....	20		
7.2.2 Photoresist	20		
7.2.3 Annular Rings	20		
7.3 PTFE Activation.....	21		
7.4 Metallization	21		
7.4.1 Plated Edge Designs	21		
7.4.2 Copper Plating.....	21		
7.5 Etching.....	22		
7.6 Bonding	22		
7.7 Multiple Material Multilayers.....	22		
7.8 Testing	22		
8 DEVICE ATTACHMENTS AND PACKAGING	22		
8.1 Attaching the Circuit to the Housing	22		
8.1.1 Mechanical Mounting	22		
8.1.2 Epoxies (both conductive and nonconductive) ..	23		
8.1.3 Thermoplastic Films.....	23		
8.1.4 Soldering.....	24		
8.1.5 Direct Bonding	24		
8.2 Connector Attachment.....	24		
8.2.1 Edge Connector	24		
8.2.2 Surface Connector	25		
8.3 Device Attachment	25		

8.3.1	Welded Bonds	26
8.3.2	Diffusion Bonding	26
8.3.3	Device Attachment	27
9	QUALITY ASSURANCE.....	27
9.1	Quality Conformance Evaluations.....	28
9.2	Reliability	28

Figure 7-2	Roll Pin	18
Figure 7-3	Straight Headless Pin (Solid)	18
Figure 7-4	Straight Headed Pin (Solid)	18
Figure 8-1	Mounting a Surface Connector to a Buried Land, Showing the Attachment of the Connector's Pin.....	25
Figure 8-2	Alternative Mounting Method, Showing the Attachment of the Connector's Pin	26

Figures

Figure 3-1	Microwave Circuit Design Flowchart.....	4
Figure 6-1	Stripline.....	12
Figure 6-2	Cutaway View of Stripline	13
Figure 6-3	Cross Sectional View of Microstrip Line without Metal Cover	14
Figure 6-4	Cross-Sectional View of Microstrip Line with Metal Cover	15
Figure 7-1	Comparison of Bilateral and True-Position Tolerancing Methods	17

Tables

Table 5-1	Typical Microwave Materials	6
Table 5-2	Typical Characteristics of Thermoplastic Bonding Films.....	9
Table 5-3	Characteristics of Thermoset Bonding Films	9
Table 5-4	Most Common Thin Copper Foils, less than 100 μm (<0.004 in, <3 oz).....	9
Table 5-5	Thick Metal Claddings.....	9